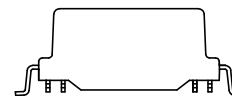
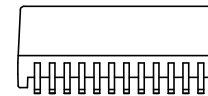
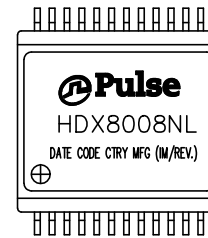




NOTES:

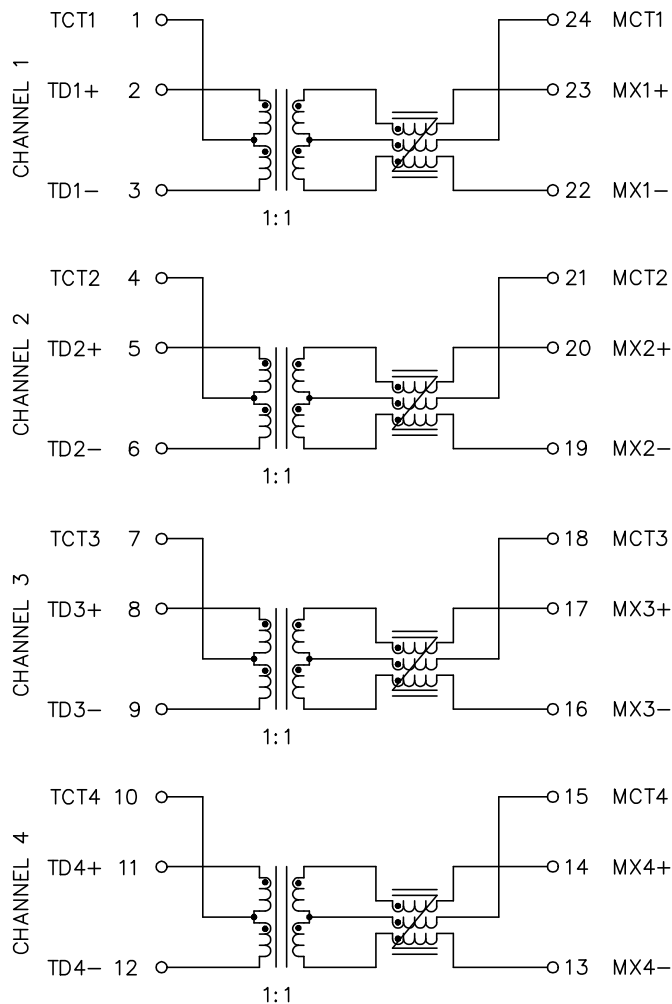
1. ROHS COMPLIANT
2. HEADER: DAP (DIALLYL PHTHALATE) WITH FLAMMABILITY RATING UL 94V-0 OR BETTER.
3. DESIGNED TO SUPPORT HD-BASET AND TESTED WITH VALENS CHIPSET
4. STORAGE TEMPERATURE: -50°C TO +125°C
5. COMPLIANCE TO J-STD:
  - A. J-STD-002: SOLDERABILITY AT 245°C REFLOW PROFILE
  - B. J-STD-020: LEVEL 1, NO MOISTURE SENSITIVE
  - C. J-STD-075: R7, 245°C MAXIMUM THROUGH REFLOW SOLDER
6. TO ORDER TAPE & REEL PACKAGING ADD A "T" SUFFIX TO THE PART NUMBER(i.e HDX8008NL BECOMES HDX8008NLT).



FINAL OUTLINE

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PRODUCT DESCRIPTION	TLA DRAWING	PS DRAWING	SHEET	PART NO.	DATASHEET REV.
MDL,SIN,HDBT,1:1,POEPP,SM,TU	HDX8008NL-P1	PS-2517.001-B	1 OF 3	HDX8008NL	C



SCHEMATIC

ELECTRICAL CHARACTERISTICS AT +25°C UNLESS OTHER SPECIFIED  
MEETS HDBASET SPECIFICATION

PARAMETER	SPECIFICATIONS		
OPERATING TEMPERATURE	-40°C TO +85°C		
URNS RATIO	1.00 ± 2%		
POLARITY	PER SCHEMATIC		
INSERTION LOSS	100 KHz	1-400 MHz	500 MHz
	-3.0 dB MAX	-2.0 dB MAX (-1.0 dB TYP)	-3.0 dB MAX
RETURN LOSS (Z OUT = 100 OHM ± 1%)	1-40 MHz	40 MHz-500 MHz	
	-20 dB MIN	-20 + 10*LOG <sub>10</sub> (f/40) MIN	
INDUCTANCE (OCL)	120 uH MIN (MEASURED AT 100 KHz, 100 mVRMS) AND WITH 10.3 mA DC BIAS		
CROSSTALK, ADJACENT CHANNELS	1-100 MHz	100-500 MHz	
	-33 dB MIN	-22 dB MIN	
COMMON MODE REJECTION RATIO	1-100 MHz	100-300 MHz	300-500 MHz
	-35 dB MIN	-30 dB MIN	-25 dB MIN
COMMON TO DIFFERENTIAL MODE REJECTION (CDMR)	1-250 MHz		250-500 MHz
	-30 dB MIN		-22 dB MIN
DC CURRENT/ VOLTAGE RATING	600 mA MAX @ 57 VDC		
INPUT - OUTPUT ISOLATION	1500 VRMS MIN @ 60 SECONDS		

NOTE: f IS FREQUENCY IN MHz.

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PRODUCT DESCRIPTION	TLA DRAWING	PS DRAWING	SHEET	PART NO.	DATASHEET REV.
MDL,SIN,HDBT,1:1,POEPP,SM,TU	HDX8008NL-P1	PS-2517.001-B	2 OF 3	HDX8008NL	C